

IN THE CLAIMS

Please amend the claims as follows:

1 – 26. (Canceled)

27. (Currently Amended) A method of manufacturing a module component comprising:
an inserting step of inserting a chip component in a first molding die;
a primary molding step of filling the first molding die with resin with a first end electrode of the chip component exposed;
a peeling step of peeling the first molding die at a side of inserting the chip component;
a secondary molding step of filling ~~the~~ a second molding die with resin with a second end electrode of the chip component; and
a forming step of forming a circuit wiring on one side or both sides of a molded element molded with resin, wherein the chip component is disposed according to a specified rule, and the chip component is molded with the resin.

28. (Previously Presented) A method according to claim 27, wherein the chip component is disposed in a specified position according to a matrix.

29. (Previously Presented) A method according to claim 28, wherein a dummy component having a same size as the chip component is inserted at a position where the chip component is not inserted according to the matrix.

30. (Canceled)

31. (Previously Presented) A method of claim 28, wherein the matrix has N aligned rows and M aligned columns, N being equal to or greater than 3, and M being equal to or greater than 3.